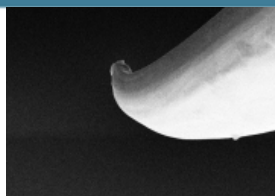




In-Situ Ion Counting for Deterministic Placement of Single Photon Emitters



FIB Capabilities
available for
user projects

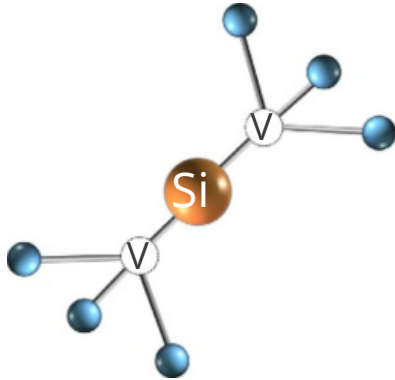
Michael Titze, Heejun Byeon, Anthony Flores,
Jacob Henshaw, Tom Harris, Andrew Mounce,
Edward S. Bielejec

12/07/2021



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Deterministic Ion Implantation



Y. Zhou et al., Nat. Comm. 8, 14451 (2017)

- Solid-state defects enable scalable quantum applications
- Color-centers are possible candidate
 - Single photon emitters require low number of ions
 - Precisely measure the conversion yield

Typical Ion Implantation Experiment:

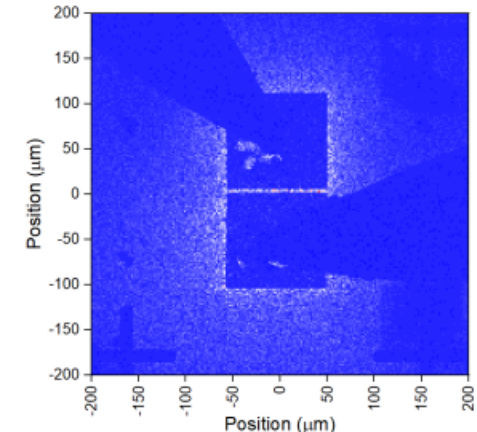
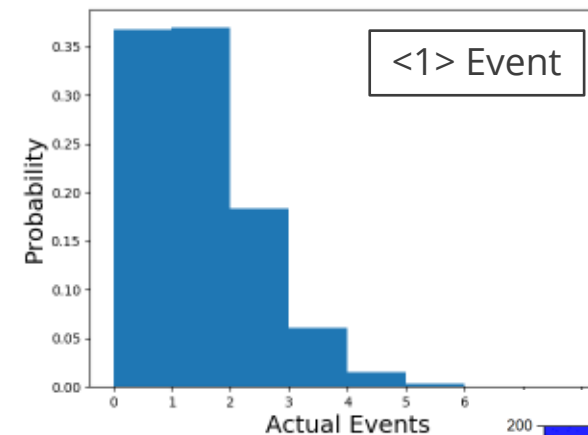
- Measure Beam Current, then do timed implantation
 - No real-time feedback of beam current
 - Limited by Poisson statistics

Our approach:

In-situ counting → Detect ions as they are implanted

In-situ photoluminescence → Detect color centers as they are formed

See EQ01.03.03 V. Chandrasekaran for details



Problems with Deterministic Defect Creation

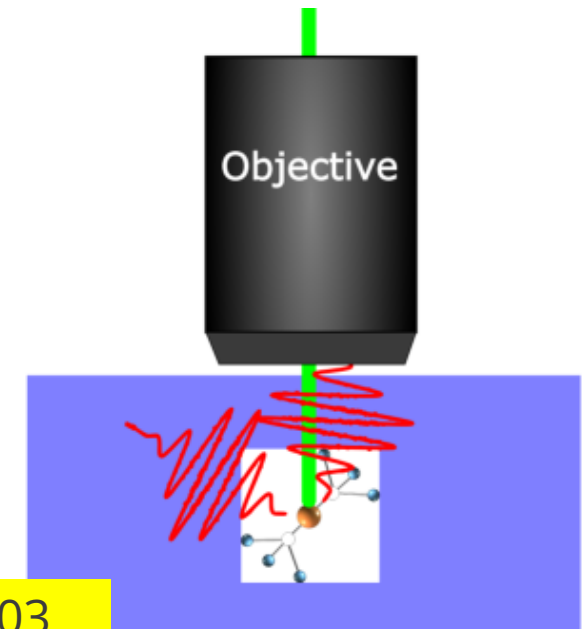
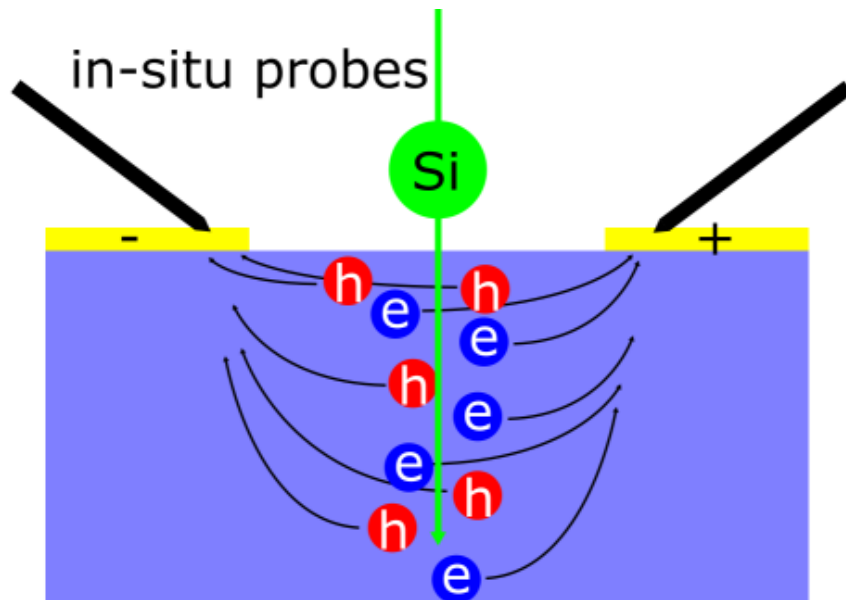
1. Few-ion implants dominated by Poisson statistics

→ In-situ counting of ions can beat Poisson statistics

$$\text{Yield} = \frac{\text{\#Measured SiV}}{\text{\#Implanted Si}}$$

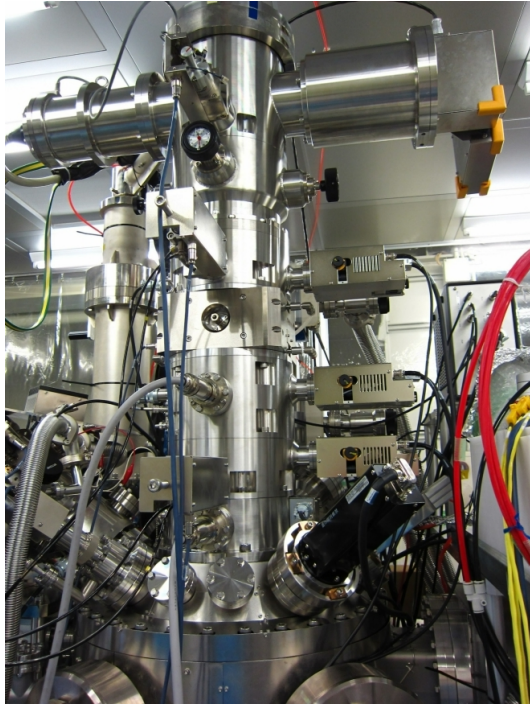
2. Low yield of optically active defects

In-situ photoluminescence (PL) measures color centers



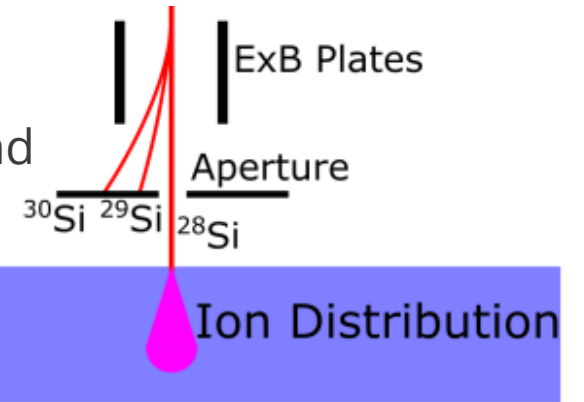
See EQ01.03.03
V. Chandrasekaran
for details

Ion Implantation for Defect Creation



A&D nanolimplanter

- Acceleration up to 100 kV → Si⁺⁺ 130 nm range in diamond
- Beam spot size <20 nm → Targeting nanostructures
- ExB mass filter → Isotopic Resolution
- Direct write lithography → Rapid Prototyping



1 H																	2 He						
3 Li	4 Be																	5 B	6 C	7 N	8 O	9 F	10 Ne
11 Na	12 Mg																	13 Al	14 Si	15 P	16 S	17 Cl	18 Ar
19 K	20 Ca	21 Sc	22 Ti	23 V	24 Cr	25 Mn	26 Fe	27 Co	28 Ni	29 Cu	30 Zn	31 Ga	32 Ge	33 As	34 Se	35 Br	36 Kr						
37 Rb	38 Sr	39 Y	40 Zr	41 Nb	42 Mo	43 Tc	44 Ru	45 Rh	46 Pd	47 Ag	48 Cd	49 In	50 Sn	51 Sb	52 Te	53 I	54 Xe						
55 Cs	56 Ba	57 La	*	72 Hf	73 Ta	74 W	75 Re	76 Os	77 Ir	78 Pt	79 Au	80 Hg	81 Tl	82 Pb	83 Bi	84 Po	85 At	86 Rn					
87 Fr	88 Ra	89 Ac	*	104 Rf	105 Db	106 Sg	107 Bh	108 Hs	109 Mt	110 Ds	111 Rg	112 Cn	113 Nh	114 Fl	115 Mc	116 Lv	117 Ts	118 Og					
			*	58 Ce	59 Pr	60 Nd	61 Pm	62 Sm	63 Eu	64 Gd	65 Tb	66 Dy	67 Ho	68 Er	69 Tm	70 Yb	71 Lu						
			*	90 Th	91 Pa	92 U	93 Np	94 Pu	95 Am	96 Cm	97 Bk	98 Cf	99 Es	100 Fm	101 Md	102 No	103 Lr						

Green: Demonstrated at SNL

Purple: Attempting at SNL

Yellow: Demonstrated at other lab

Green: Demonstrated at SNL

Purple: Attempting at SNL

Yellow: Demonstrated at other lab

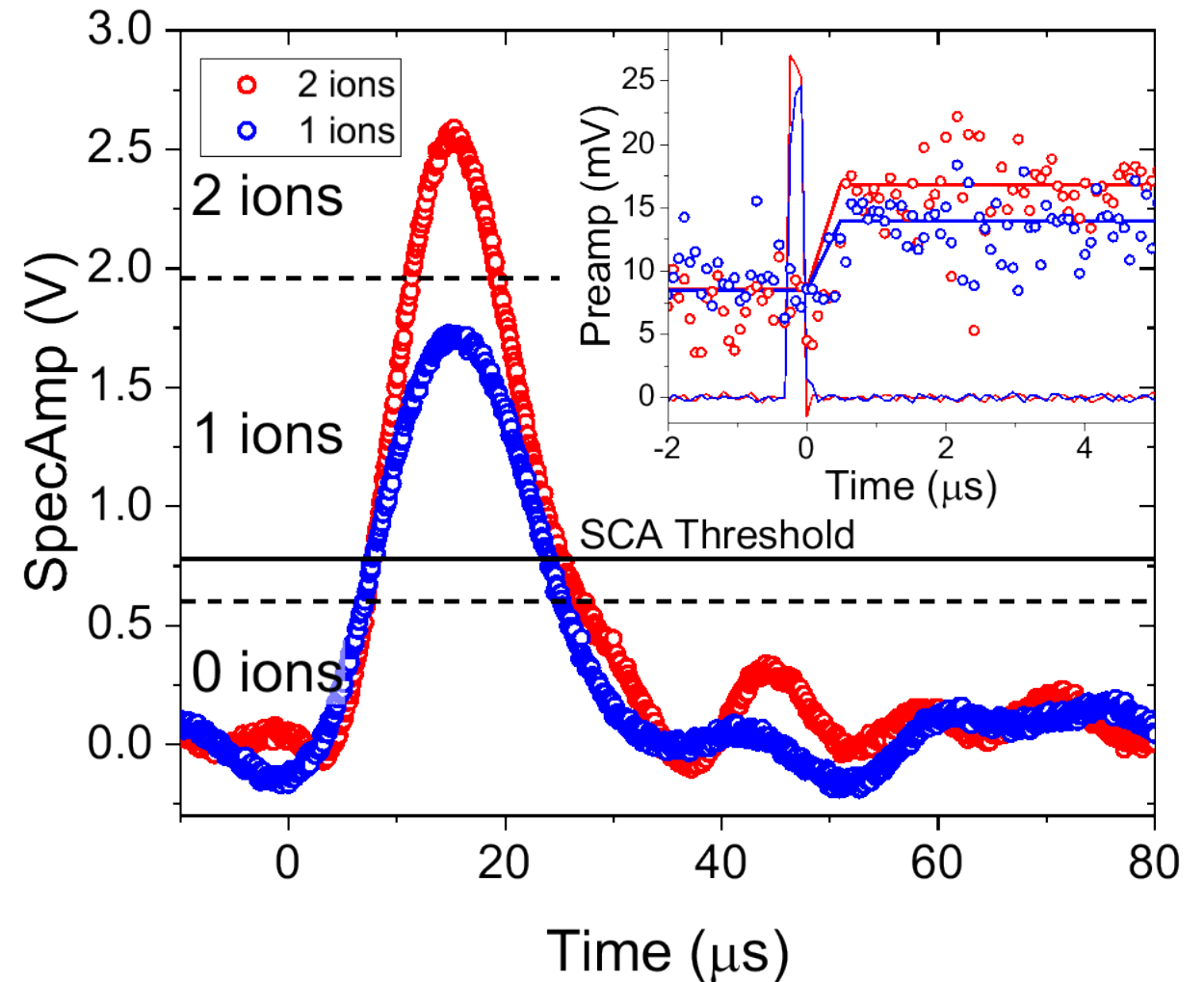
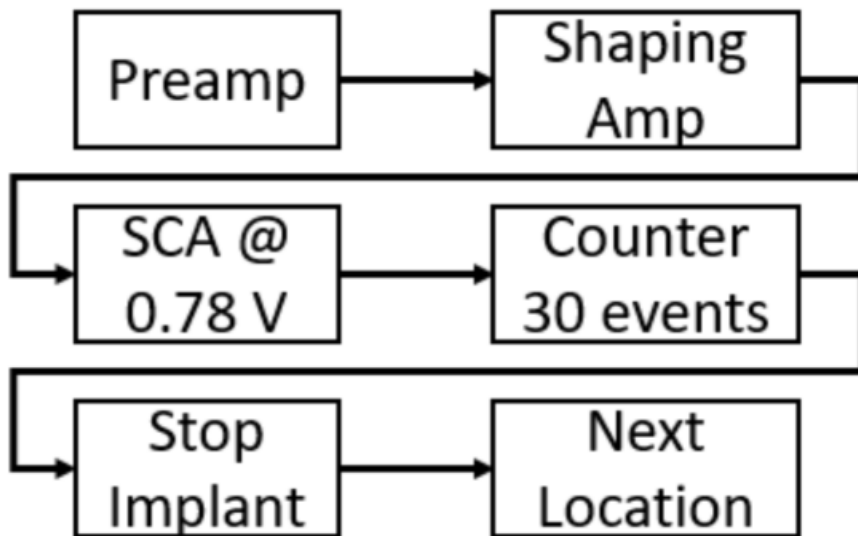
5 In-Situ Ion Counting

Experimental Setup:

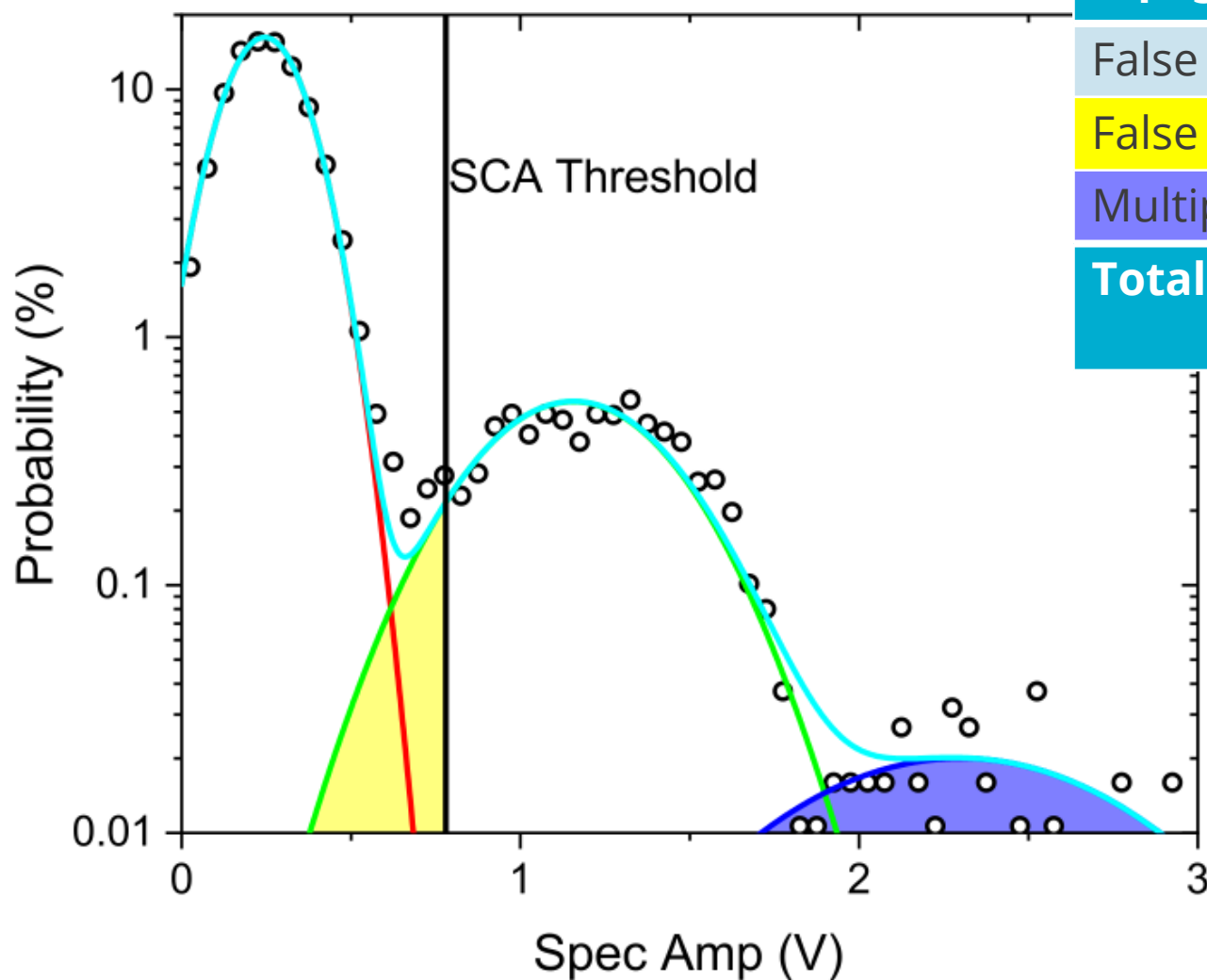
Triggered Implantation

Count Ions using SCA

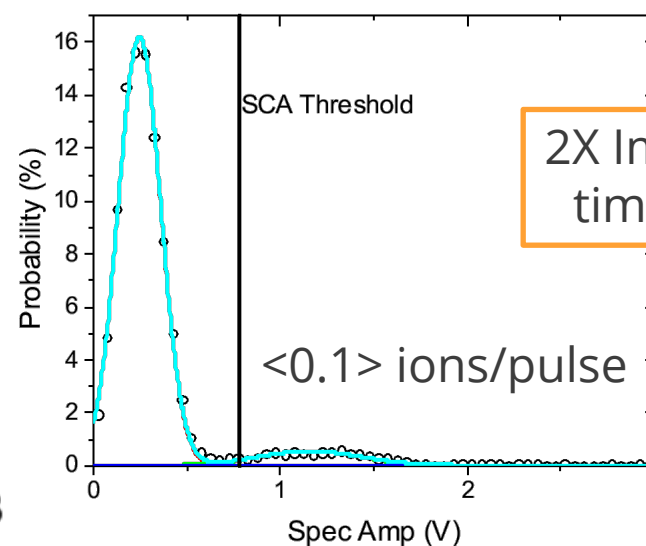
All Events are recorded on oscilloscope



In-Situ Ion Counting – Errors

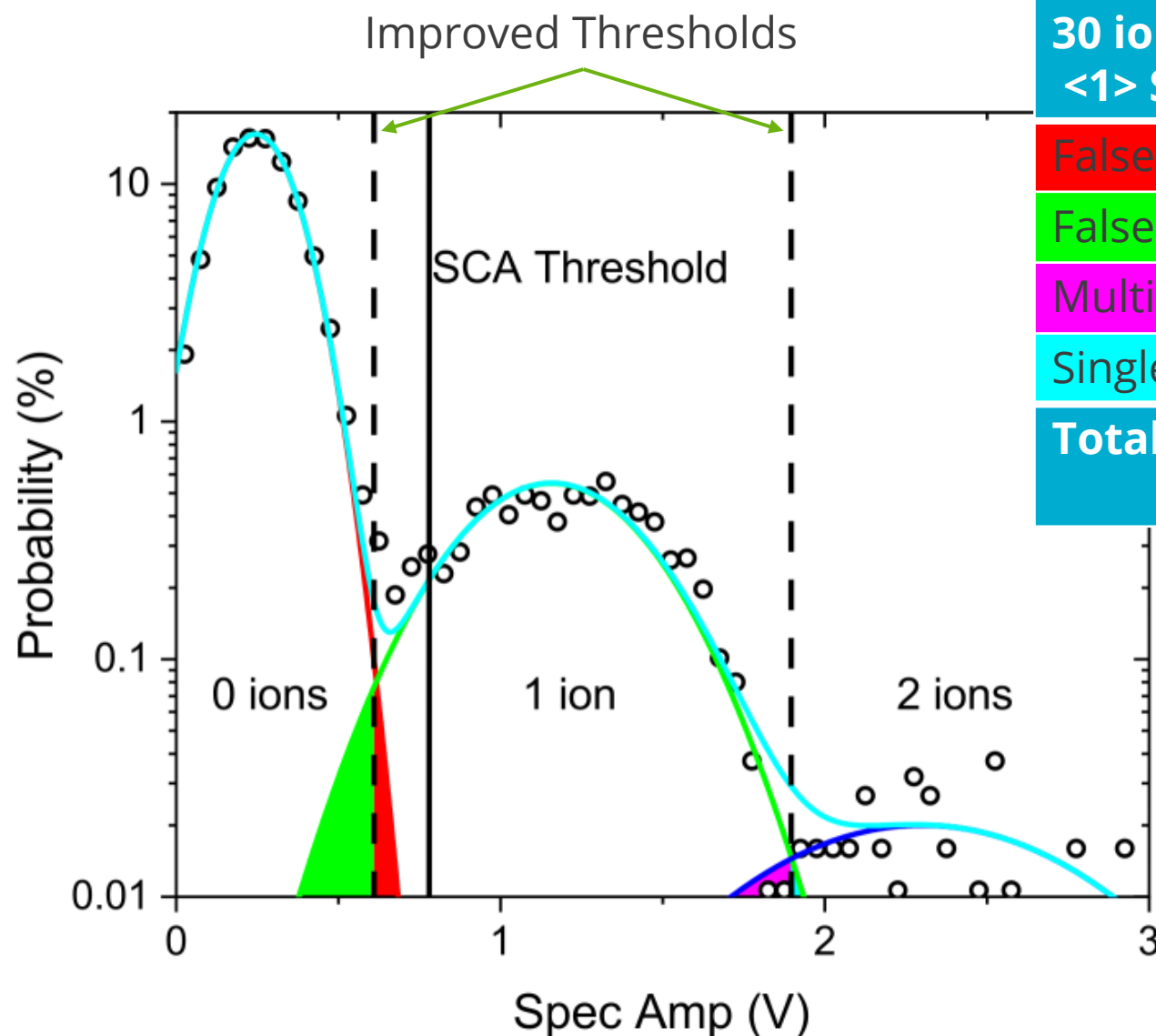


30 ions / <1> SiV	Timed	In-Situ
False Positives	-	< -1 ppb
False Negatives	-	8.6 %
Multiple Ions	-	5.8 %
Total	+18.3 / -18.3 %	+14.4 / -0 %



2X Improvement over
timed implantation

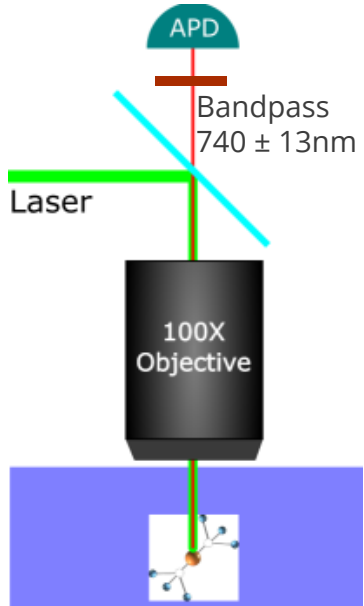
Post-Implantation Analysis – Improved Errors



30 ions / <1> SiV	Timed	In-Situ	Post-Analysis
False Positives	-	< -1 ppb	2.3 %
False Negatives	-	8.6 %	-0.9 %
Multiple Ions	-	5.8 %	1.7 %
Single as Double	-	-	-0.2 %
Total	+18.3 / -18.3 %	+14.4 / -0 %	+4.0 / -1.1 %

7X Improvement over
timed implantation

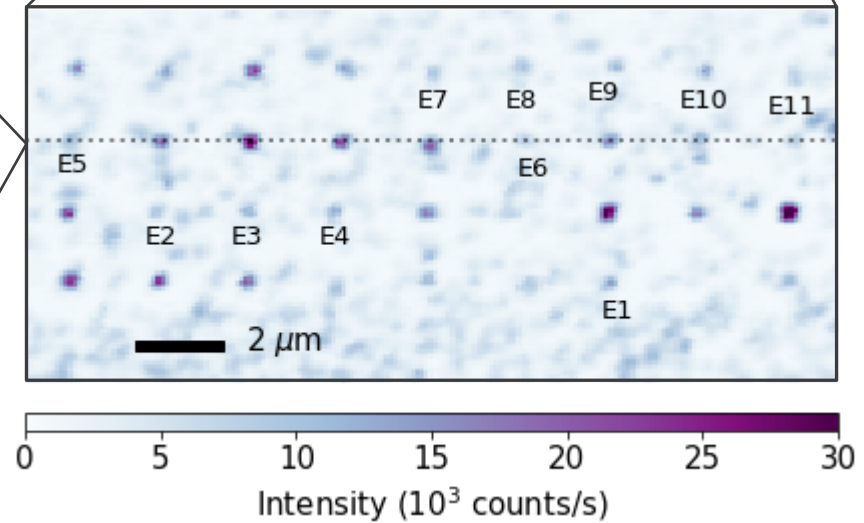
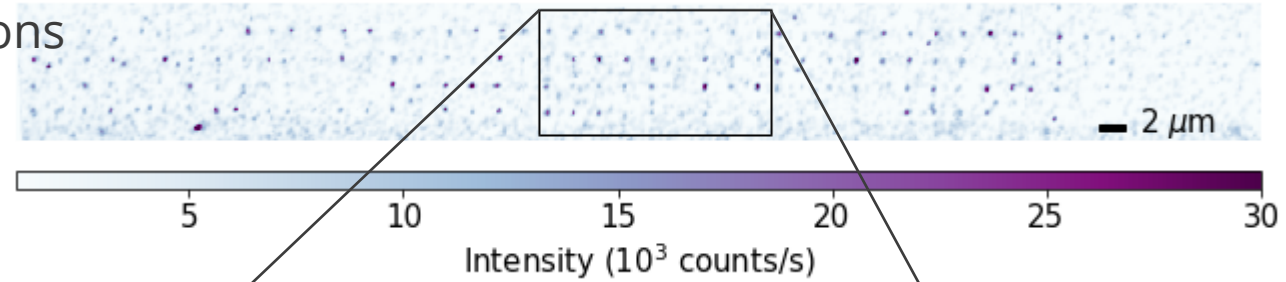
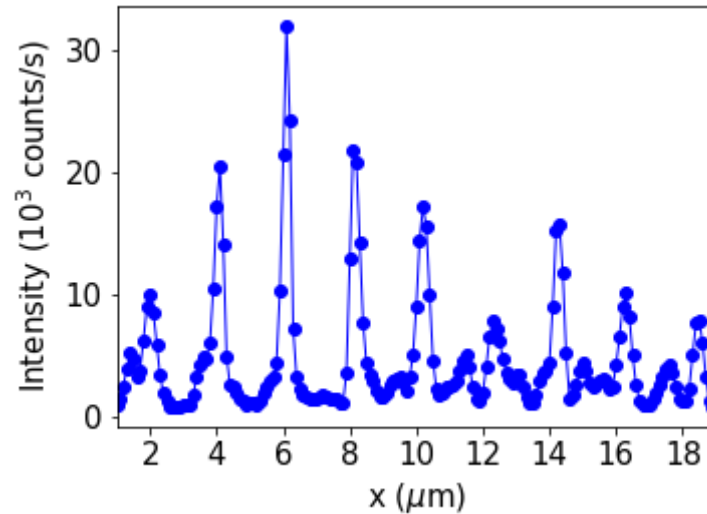
Photolumuminescence of Counted Sample



$$\text{Yield} = \frac{\# \text{Measured SiV}}{\# \text{Implanted Si Ions}}$$

High confidence in implanted # of ions

→ Instead of +/- 5 ion error bar on #Si ions, reduce to +1.2/-0.33 ions



Yield Measurement on Counted Sample



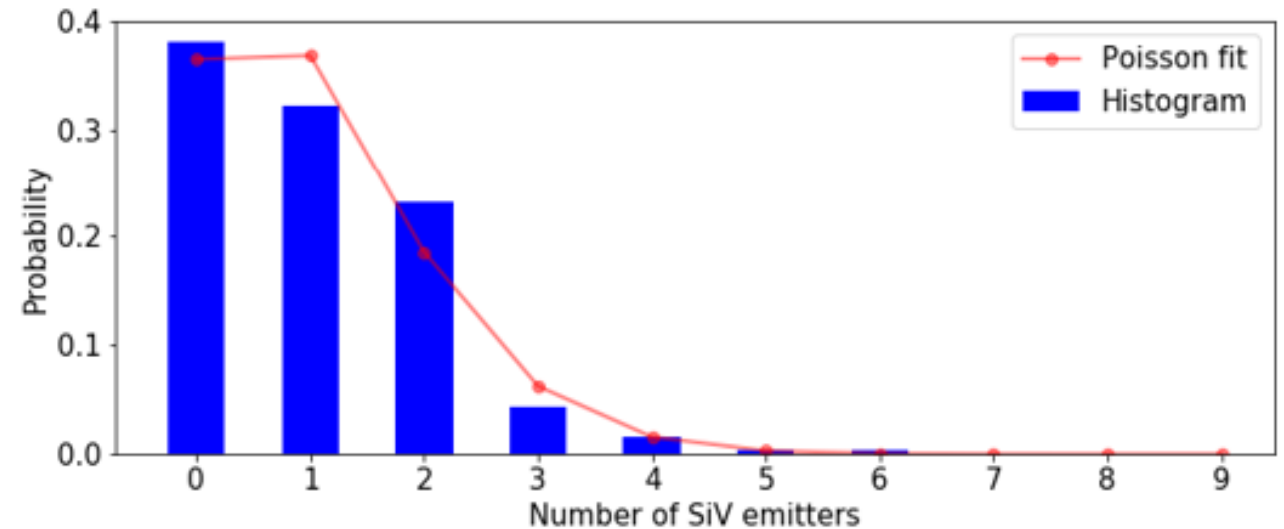
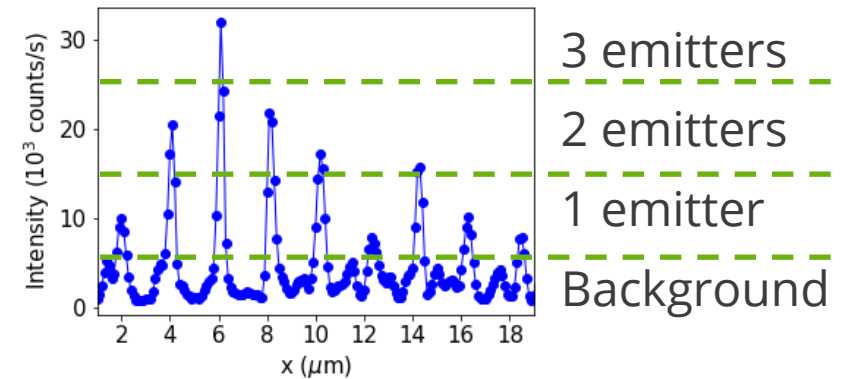
Implanted $\langle 33.8 \rangle$ ions/spot

$\langle 1.01 \rangle \pm 0.07$ emitter per location

$$\text{Yield} = \frac{1.01 \pm 0.07}{33.8 + 1.4 / -0.4} = 2.98^{+0.21}_{-0.24} \&$$

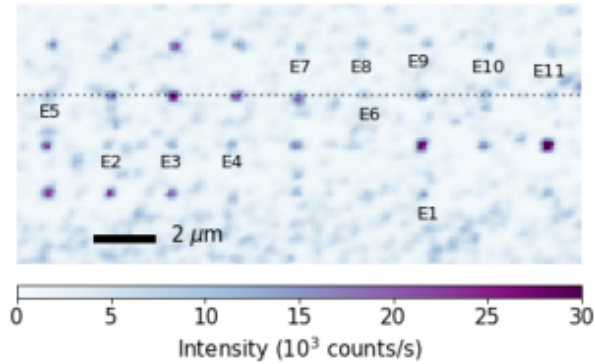
Is our classification correct?

→ Hanbury-Brown-Twiss interferometry



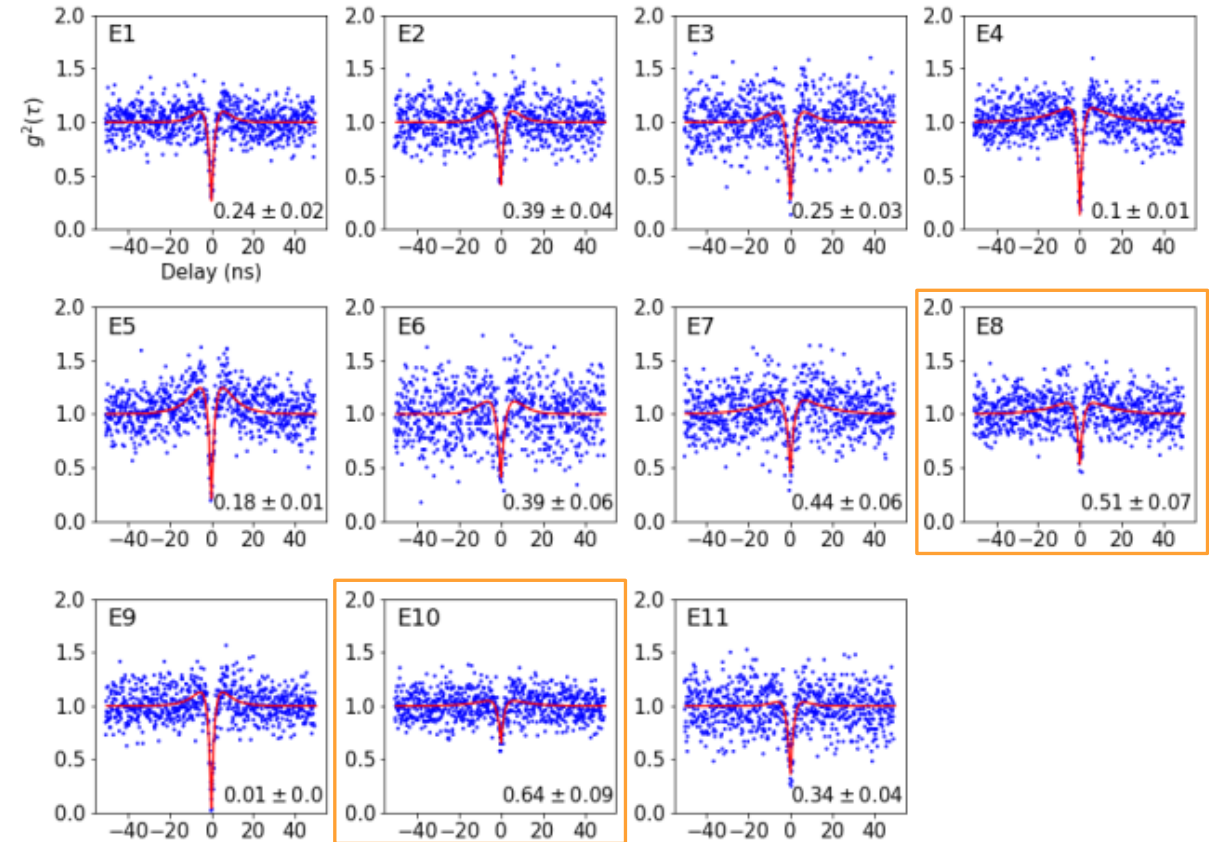
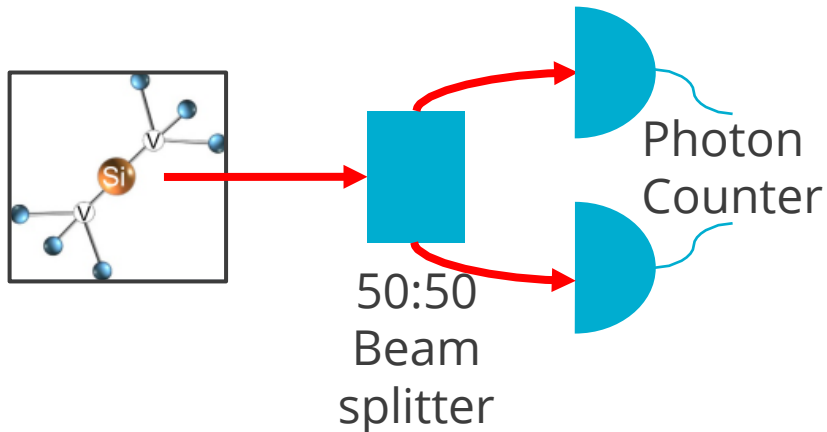
Our error $\leq 10\%$,
literature reports $\geq 30\%$

Hanbury-Brown-Twiss Interferometry



Single emitter will emit only 1 photon at a time

→ Only 1 photon at each counter at any time



18 % of locations identified as single emitters from PL are not single emitters

Discussion – Additional Emitters

18 % of emitters classified as SPE by PL contain a 2nd emitter

Possible explanation: Overlap between SiV + NV

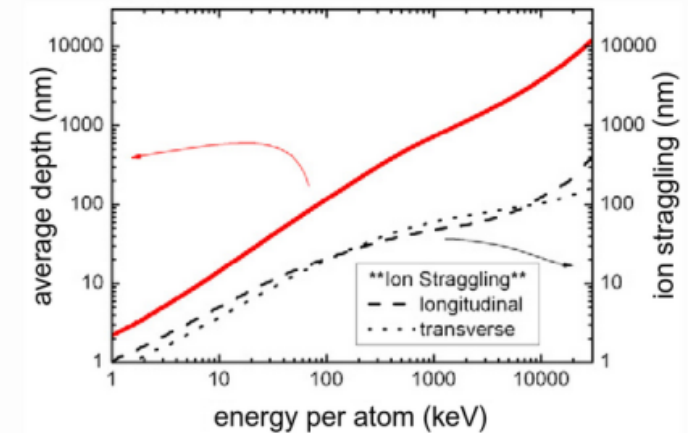
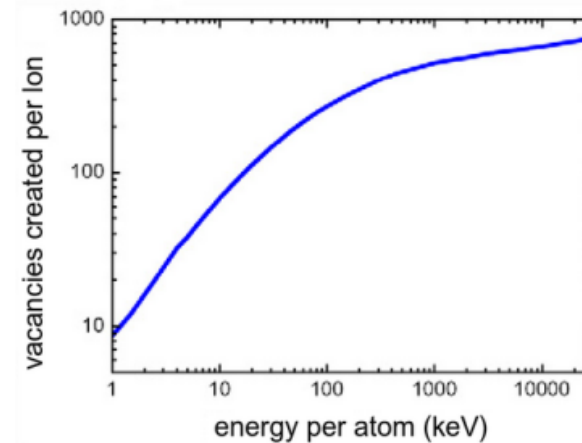
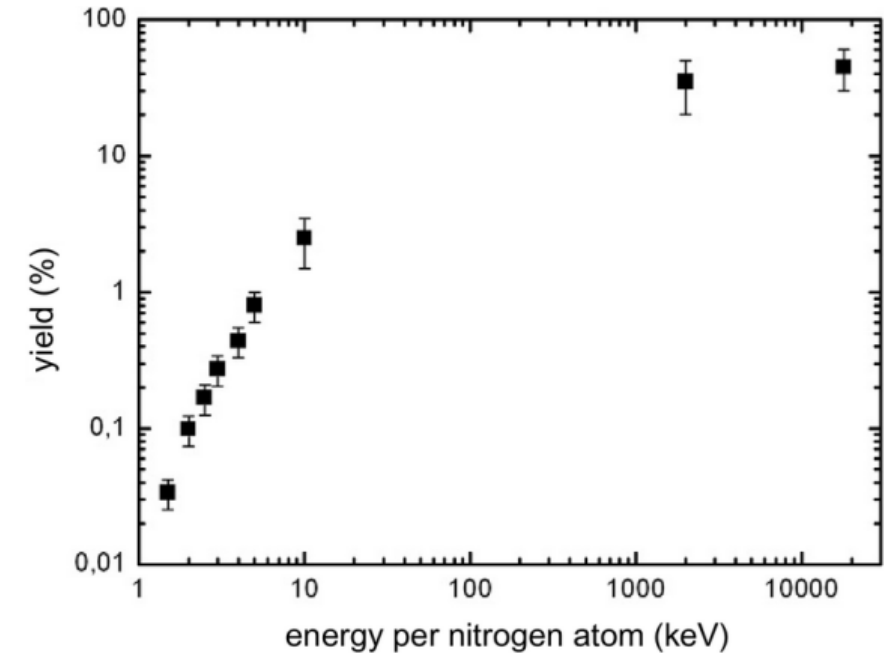
NV is created from native N during high-temperature anneal

Average NV Separation (nm)		Native N Content	
		1 ppb	0.1 ppb
Conversion Yield	45 %	230	497
	10 %	381	820

Our excitation volume is 340 nm and 18 % of emitters have 2nd emitter

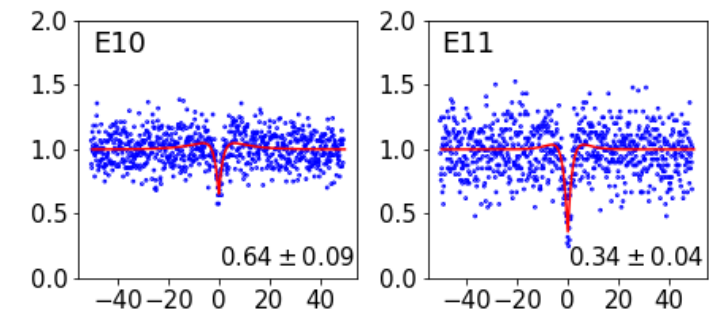
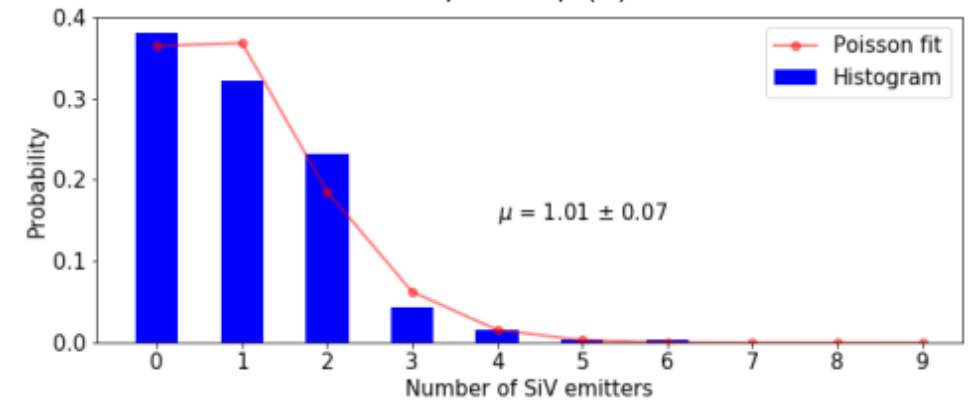
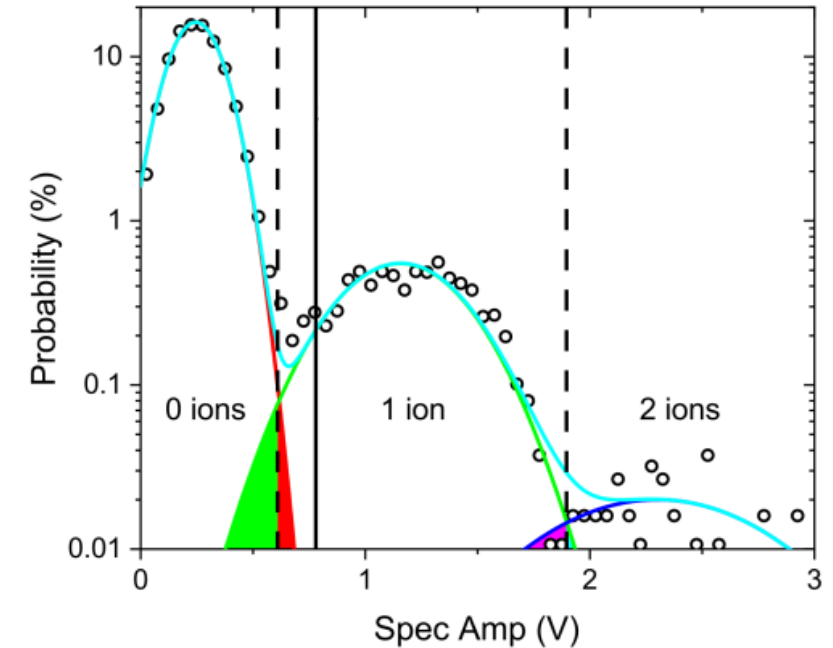
→ If due to NV ~10 % conversion yield, 1 ppb N content

→ If due to SiV, yield 3.54 %



Conclusion of In-Situ Counting

- In-situ single ion counting can improve confidence on number of ions to +4 / -1.1 %
- For implantation of 30 ions / $\langle 1 \rangle$ SiV, 7X improvement over timed implantation
 - For implantation of fewer ions, improvement will be even greater
- PL confirms we implanted $\langle 1 \rangle$ SiV
- HBT shows that 18 % of locations classified as single emitters based on PL are not single emitters
 - Likely due to natively occurring N being converted to NV during high-temperature annealing



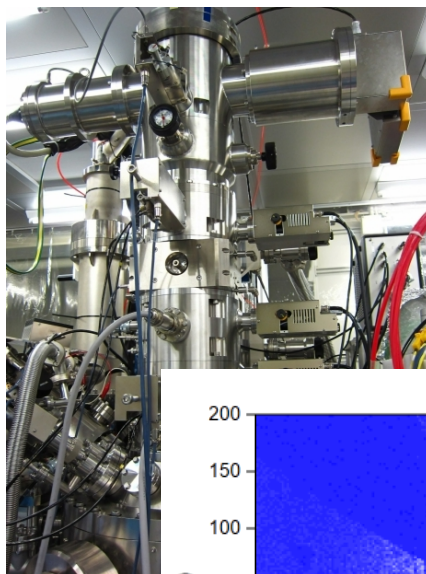
Conclusion

Demonstrated high-resolution
implantation for scalable quantum
applications

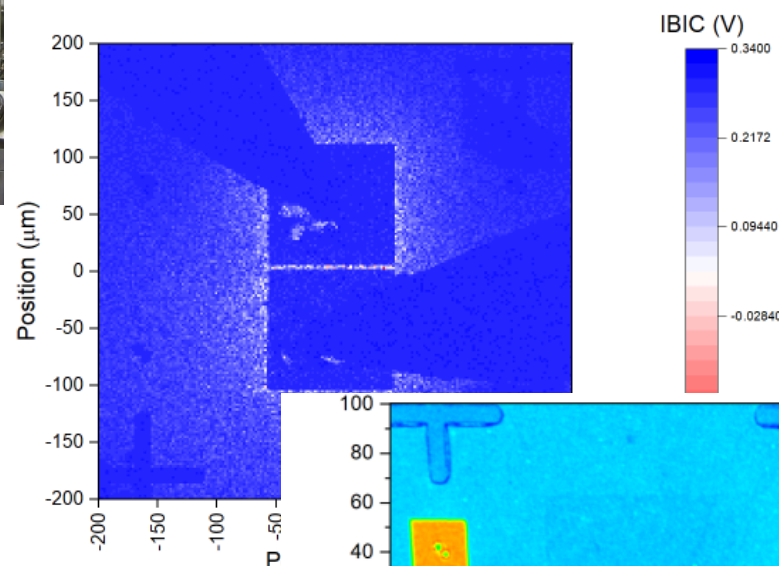
Low yield is roadblock to making
devices

In-situ ion counting and in-situ
PL for deterministic defect
centers.

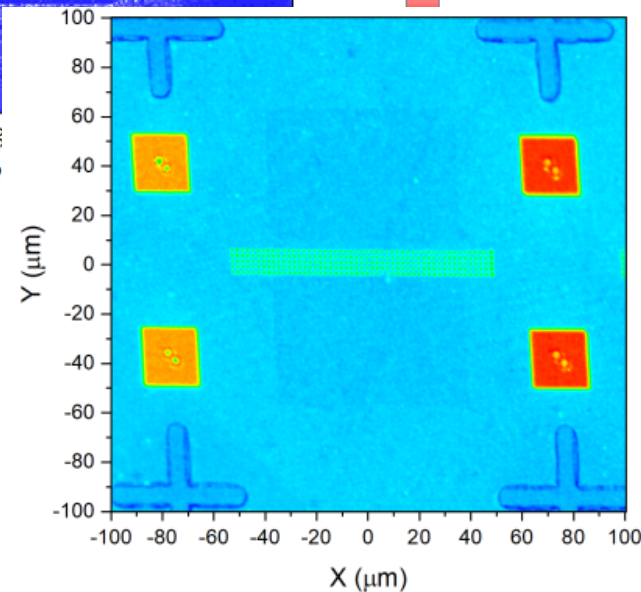
Future in-situ laser annealing
will enable SiV, GeV, ... in
diamond



FIB Implantation



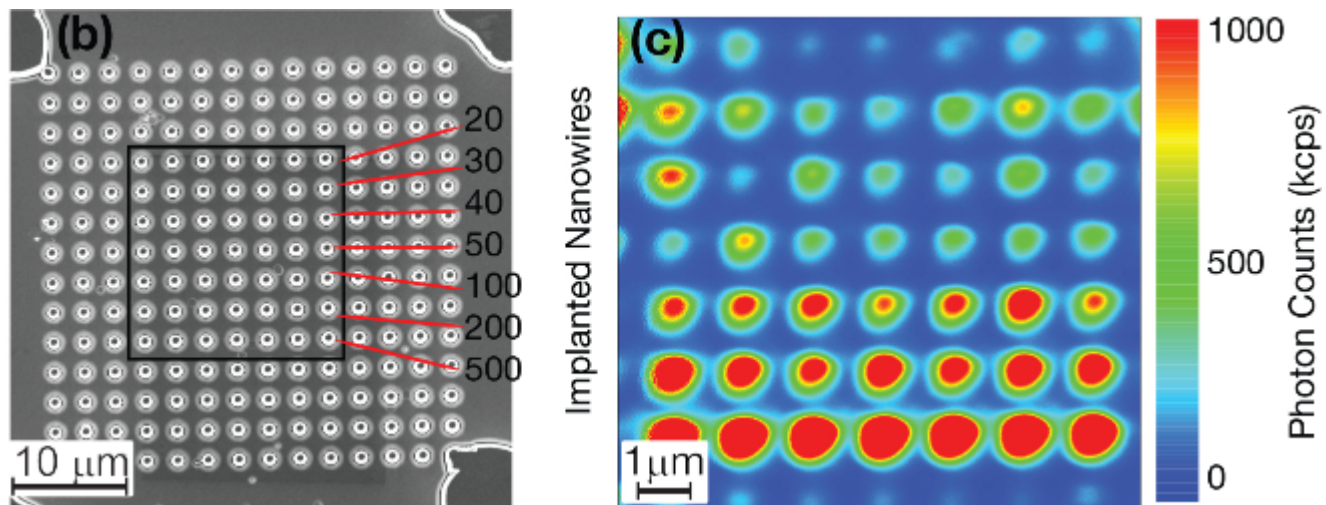
Integration into Nanostructures



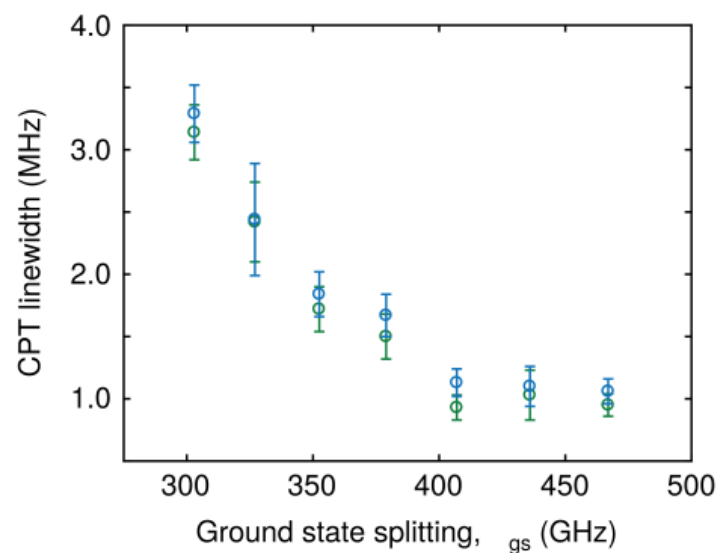
Enabling new devices



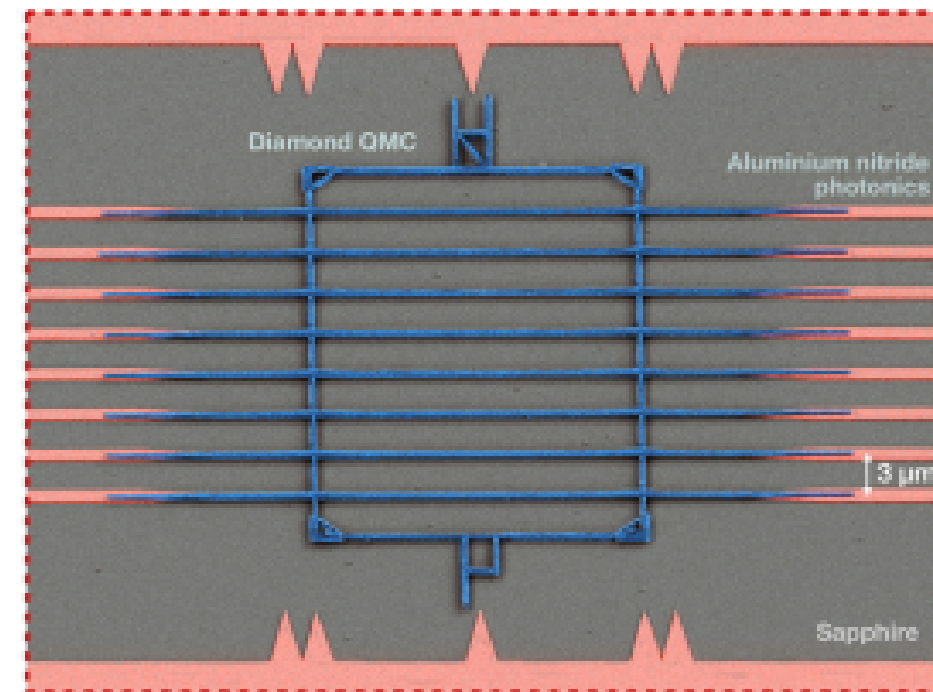
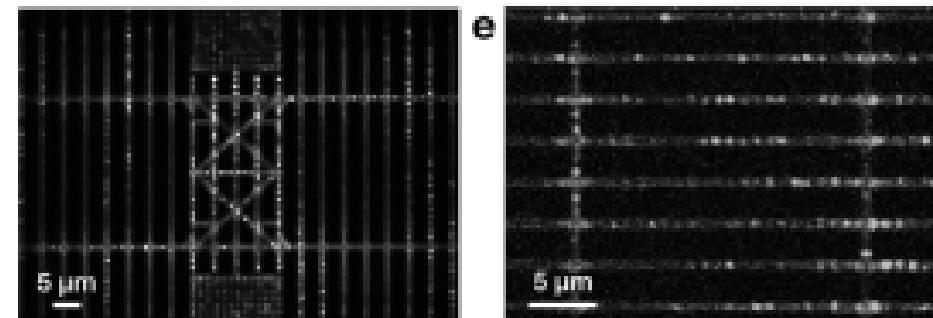
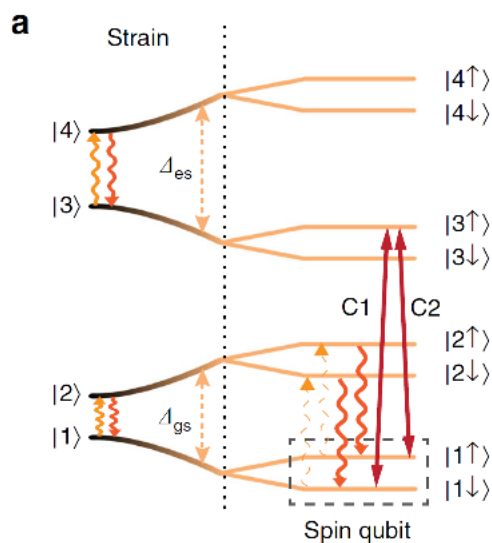
Examples of FIB Implantation



L. Marseglia et al., Opt. Express 26, 80 (2018)



Y.-I. Sohn et al., Nat. Commun. 9, 2012 (2018)



Noel H. Wan et al., arXiv 1911.05265 (submitted)